

said circuit board with solder balls, and spaces between solder connected parts are filled with an underfilling material which consists essentially of a one-pack type thermosetting urethane composition comprising:

a urethane prepolymer having a terminal isocyanate group, which is obtained by reacting a polyol with an excessive amount of a polyisocyanate, wherein said urethane prepolymer is a mixture of a urethane prepolymer having a terminal isocyanate group comprising a hydrocarbon polyol as a polyol and a urethane prepolymer having a terminal isocyanate group comprising a polyoxyalkylene polyol in a weight ratio of 9:1 to 2:8, and

a fine powder-coated curing agent comprising a curing agent which is in a solid state at room temperature and surface active sites of which are covered with a fine powder.

13. The mounted board according to claim 12, wherein said curing agent which is in a solid state at room temperature is at least one curing agent selected from the group consisting of imidazole compounds, imidazoline compounds, amine compounds, guanidine compounds, acid anhydrides, dibasic carboxylic acid dihydrazide, guanamines, melamine and amine adducts.

14. The mounted board according to claim 12, wherein said fine powder is one material selected from the group consisting of titanium oxide, calcium carbonate, clay, silica, zirconia, carbon, alumina, talc, polyvinyl chloride, acrylic resins, polystyrene and polyethylene.